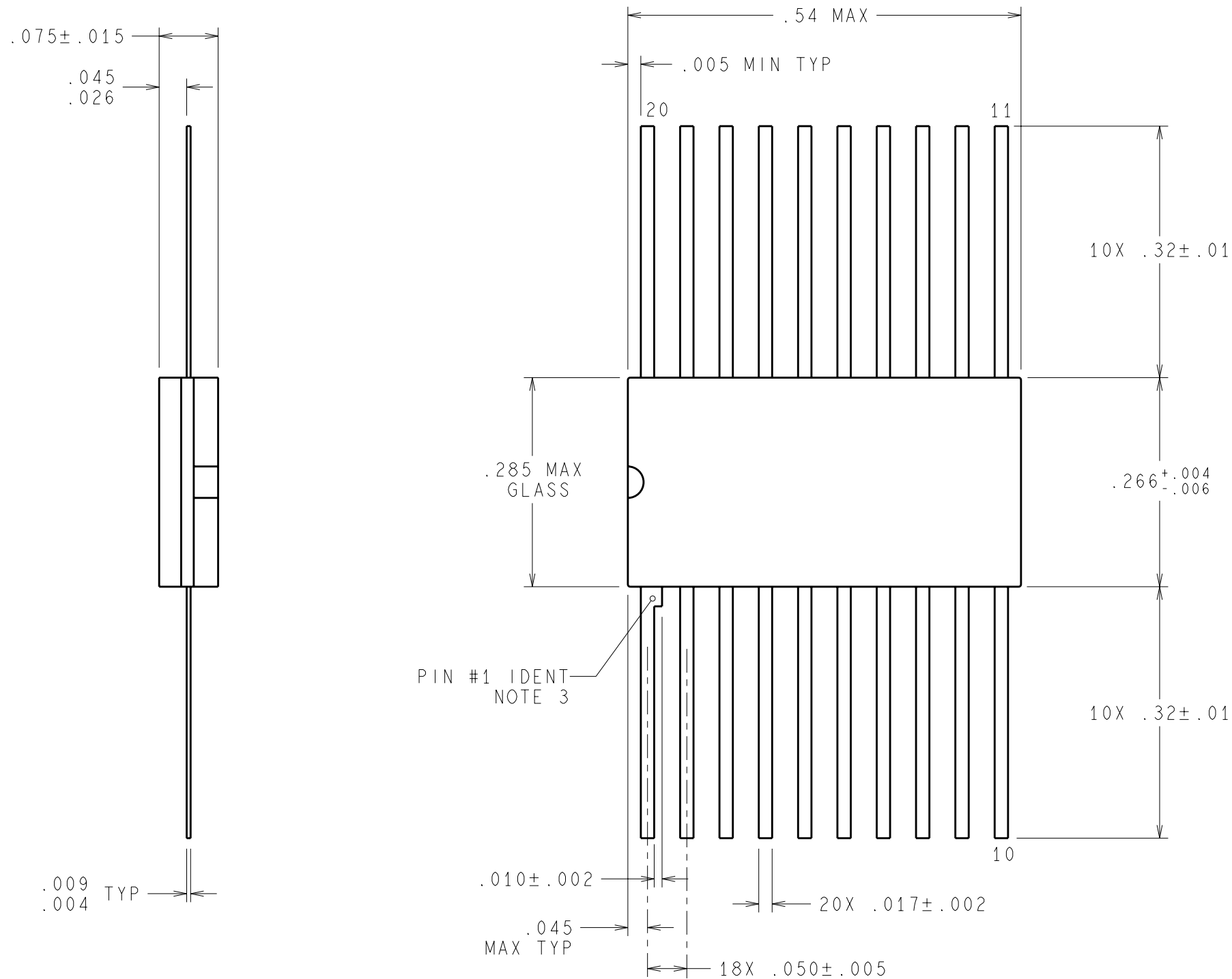


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
F	REVISE AND REDRAW PER NEW STANDARD.	10512	07/28/1994	DEG/AP
G	DIM .045/.026 WAS .035±.005; REVISE NOTE 1; UPDATE NOTE 4, MIL/AERO STAMPS & TITLE; CHANGE DWG FORMAT TO B SIZE.	1161	09/08/2003	MS/SWK
H	DIM .009/.004 WAS .005±.001; DELETE NOTE 2 AND ITS REFERENCE; RENUMBER NOTES & UPDATE NEW NOTE 3.	1574	08/30/2004	MS/RW
J	DIM .017±.002 WAS .017±.020; UPDATE NOTE 3.	2120	07/18/2006	MS/KS



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- LEAD 1 IDENTIFICATION SHALL BE:
 - A NOTCH OR OTHER MARK WITHIN THIS AREA.
 - A TAB ON LEAD 1, EITHER SIDE.
- NO JEDEC REGISTRATION AS OF JULY 2006.

DIMENSIONS ARE IN INCHES

MIL-STD-1835B
CONFIGURATION CONTROL

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	CERPACK, .540 X .266 X .075 BODY, 20 LD, .050 PITCH		
DRAWN DE Grady	07/28/1994				
DFTG. CHK. KURT SINCERBOX	07/18/2006				
ENGR. CHK. KURT SINCERBOX	07/18/2006				
PROJECTION 1 INCH		SCALE NTS	SIZE B	DRAWING NUMBER (SC)MKT-W20A	REV J
FORMERLY: N/A		SHEET 1 of 1			